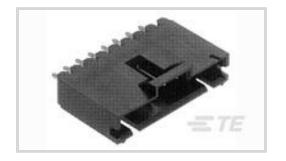
103670-4 - ACTIVE

AMPMODU | AMPMODU MTE

TE Internal #: 103670-4 PCB Mount Header, Vertical, Wire-to-Board, 5 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, Signal, AMPMODU MTE

View on TE.com >

Connectors > PCB Connectors > PCB Headers & Receptacles



Connector System: Wire-to-Board

Number of Positions: 5

Number of Rows: 1

Centerline (Pitch): 2.54 mm [.1 in]

PCB Mount Orientation: Vertical

Features

Product Type Features

Connector System	Wire-to-Board
Header Type	Fully Shrouded
Sealable	No



Connector & Contact Terminates To	Printed Circuit Board
PCB Connector Assembly Type	PCB Mount Header
Configuration Features	
Number of Positions	5
Number of Rows	1
PCB Mount Orientation	Vertical
Electrical Characteristics	
Termination Resistance	15 mΩ
Insulation Resistance	5000 ΜΩ
Dielectric Withstanding Voltage (Max)	600 V
Body Features	
Primary Product Color	Black
Contact Features	
Contact Mating Area Length	5.84 mm[.23 in]
Mating Square Post Dimension	.64 mm[.025 in]

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PCB Mount Header, Vertical, Wire-to-Board, 5 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, Signal, AMPMODU MTE



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Operation/Application	
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Usage Conditions	
PCB Thickness (Recommended)	1.57 mm[.062 in]
Connector Height	13.59 mm[.535 in]
Connector Length	15.24 mm[.6 in]
Dimensions	
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	Thermoplastic
Housing Features	
PCB Mount Retention	With
PCB Mount Alignment	Without
Mating Alignment	With
Connector Mounting Type	Board Mount
Mating Retention Type	Hold-Down
PCB Mount Retention Type	Swaged Retention Tails
Mating Retention	With
Mating Alignment Type	Latched, Polarization
Mechanical Attachment	
Termination Method to Printed Circuit Board	Through Hole - Solder
Termination Post & Tail Length	3.3 mm[.13 in]
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Features	
Contact Current Rating (Max)	3 A
Contact Type	Pin
Contact Mating Area Plating Material	Gold
Contact Base Material	Brass
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Shape & Form	Square
PCB Contact Termination Area Plating Material Finish	Matte
Contact Mating Area Plating Material Thickness	.381 µm[15 µin]
PCB Contact Termination Area Plating Material Thickness	2.54 μm[100 μin]

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PCB Mount Header, Vertical, Wire-to-Board, 5 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, Signal, AMPMODU MTE



	Signal
Circuit Application	Signal
ndustry Standards	
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	35
Packaging Type	Box, Tube
·	
•	Not Compliant
Product Compliance for compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU EU ELV Directive 2000/53/EC	Not Compliant Compliant with Exemptions
For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU	
For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU EU ELV Directive 2000/53/EC	Compliant with Exemptions Restricted Materials Above Threshold Current ECHA Candidate List: JUNE 2023
Tor compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU EU ELV Directive 2000/53/EC China RoHS 2 Directive MIIT Order No 32, 2016	Compliant with Exemptions Restricted Materials Above Threshold Current ECHA Candidate List: JUNE 2023 (235)
Tor compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU EU ELV Directive 2000/53/EC China RoHS 2 Directive MIIT Order No 32, 2016	Compliant with Exemptions Restricted Materials Above Threshold Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE
Tor compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU EU ELV Directive 2000/53/EC China RoHS 2 Directive MIIT Order No 32, 2016	Compliant with Exemptions Restricted Materials Above Threshold Current ECHA Candidate List: JUNE 2023 (235)
Tor compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU EU ELV Directive 2000/53/EC China RoHS 2 Directive MIIT Order No 32, 2016	Compliant with Exemptions Restricted Materials Above Threshold Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235)
Tor compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU EU ELV Directive 2000/53/EC China RoHS 2 Directive MIIT Order No 32, 2016	Compliant with Exemptions Restricted Materials Above Threshold Current ECHA Candidate List: JUNE 2 (235) Candidate List Declared Against: JUN

handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Reflow solder capable to 260°C

Halogen Content

Solder Process Capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

PCB Mount Header, Vertical, Wire-to-Board, 5 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, Signal, AMPMODU MTE





Also in the Series | AMPMODU MTE

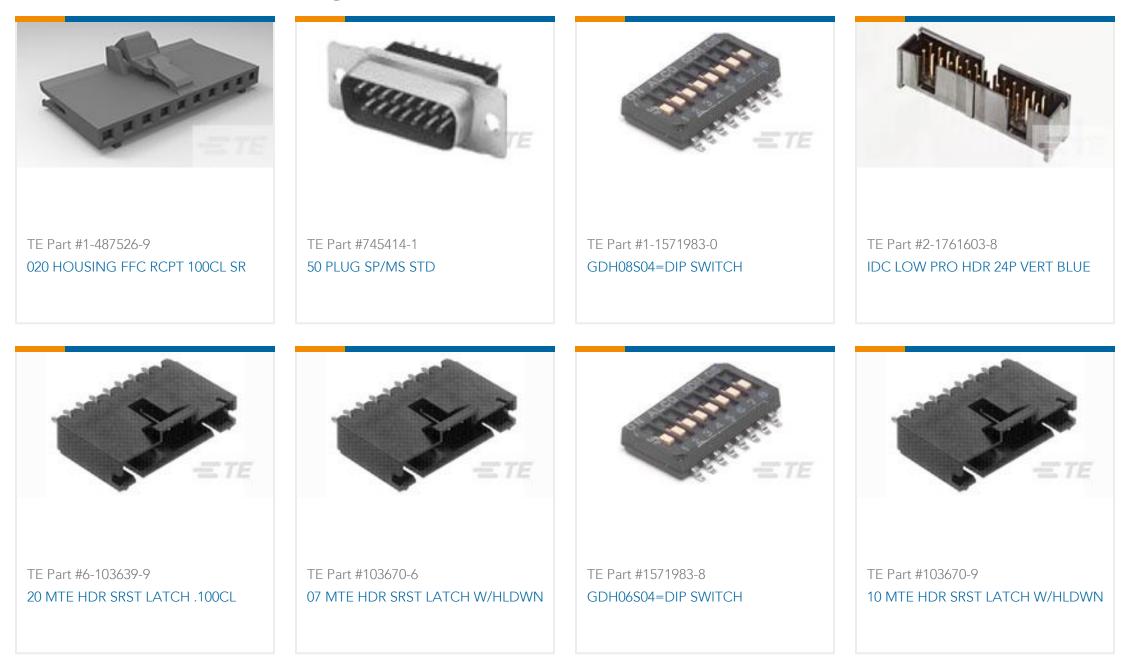


Standard Rectangular Connectors(2)

Wire-to-Board Connector Assemblies & Housings(585)

Wire-to-Board Connector Contacts(32)

Customers Also Bought



PCB Mount Header, Vertical, Wire-to-Board, 5 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, Signal, AMPMODU MTE



TE Part #2149730-2 SFP+ Enhanced 1x4 Cage, PCI Heatsink

Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_103670-4_T.2d_dxf.zip

English

Customer View Model ENG_CVM_CVM_103670-4_T.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_103670-4_T.3d_stp.zip

English

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Datasheets & Catalog Pages AMPMODU MTE INTERCONNECT SYSTEM

English

Product Specifications Application Specification

English

Product Environmental Compliance

Product Compliance Document

English

Product Compliance Document

English

Instruction Sheets Instruction Sheet (U.S.)

English